

**The Claims:**

Following is a complete listing of the claims pending in the application.

1. (Previously presented) A method for assembling microelectronic dies, comprising:

placing a base die on a substrate in a die attach machine so that a front side of the base die with bond pads faces toward the substrate and a backside of the base die faces away from the substrate; and

stacking a first stacked die onto the backside of the base die in the same die attach machine by dispensing an adhesive onto the backside of the base die and placing a backside of the first stacked die onto the adhesive, wherein the first stacked die is stacked onto the base die before securing the base die to the substrate in a heating cycle.

2. (Previously presented) The method of claim 1, further comprising heating the base die and the first stacked die in a single heating cycle to secure the base die to the substrate and to secure the first stacked die to the base die.

3-7. (Cancelled)

8. (Previously presented) The method of claim 1 wherein placing the base die and stacking the first stacked die occur without loading the substrate and the base die into a separate die attach machine.

9. (Original) The method of claim 1, further comprising placing the base die on the substrate and stacking the first stacked die onto the base die in a single pass through a single die attach machine.

10. (Previously presented) A method for assembling microelectronic dies, comprising:

preparing a substrate to receive a base die in a die attach machine;

placing the base die on the substrate in the die attach machine so that a front side of the base die with bond pads faces toward the substrate and a backside of the base die faces away from the substrate;

moving the base die within the same die attach machine without heating the base die; and

stacking a first stacked die onto the base die in the die attach machine by dispensing an adhesive onto the backside of the base die and placing the first stacked die onto the adhesive.

11. (Original) The method of claim 10, further comprising heating the base die and the first stacked die in a single heating cycle to secure the base die to the substrate and to secure the first stacked die to the base die.

12-47. (Cancelled)

48. (Previously presented) The method of claim 1 wherein placing the base die on the substrate comprises positioning a flip chip on the substrate.

49. (Previously presented) The method of claim 1 wherein dispensing the adhesive onto the backside of the base die comprises depositing an epoxy onto the base die.

50. (Previously presented) The method of claim 10 wherein placing the base die and stacking the first stacked die occur without loading the substrate and the base die into a separate die attach machine.

51. (Previously presented) The method of claim 10 wherein placing the base die on the substrate and stacking the first stacked die onto the base die occur in a single pass through the die attach machine.

52. (Previously presented) The method of claim 10 wherein placing the base die on the substrate comprises positioning a flip chip on the substrate.

53. (Previously presented) The method of claim 10 wherein dispensing the adhesive onto the backside of the base die comprises depositing an epoxy onto the base die.